

# TDES9640 V<sup>3</sup>Link™ Deserializer Hub With CSI-2 Output Ports for 8-MP+ Cameras and Other Sensors

## 1 Features

- Quad 7.55 Gbps deserializer hub aggregates data from up to 4 sensors simultaneously
  - Supports 8MP+ imagers
  - Single-ended coaxial or shielded twisted-pair (STP) cable
  - Power-over-coax (PoC) support
- Supports 3 data rates: 7.55 Gbps, 3.775 Gbps and 1.8875 Gbps
- CSI v2.1 compliant system interface
- Supports up to 2 MIPI CSI-2 output ports and 1 replication port
  - CSI Port 0: MIPI CSI-2 output port
  - CSI Port 1: MIPI CSI-2 output port
  - CSI Port 2: replication port (D-PHY only)
  - 16 Virtual channels and VC-ID remapping
  - MIPI D-PHY and C-PHY configurable
- MIPI D-PHY v2.1 compatible
  - Up to 4 data lanes with 2 clocks per port
  - Up to 2.5 Gbps per lane, 10 Gbps per port
- MIPI C-PHY v1.1 compatible
  - Up to 4 trios per port
  - Up to 5.7 Gbps per trio, 22.8 Gbps per port
- Quad CMLOUT output ports for off-board processing
  - 4 x CMLOUT ports replicated from 4 x V<sup>3</sup>Link RX ports
  - Capable of driving another deserializer at the same line rate
- 10 GPIO pins for sensor synchronization and diagnostics
- Dual I2C ports
- Frozen frame detection
- Automatic receiver equalization
- Compatible with TSER9615, TSER953, and with the TSER4905 (when used in Enhanced Vision mode)
- Low power sleep mode with GPIO-state retention
- Wide temperature range: -20°C to 85°C

## 2 Applications

- [Appliances](#)
- [Video Surveillance](#)
- [Elevators and Escalators](#)
- [Industrial Robots](#)
- [Machine Vision](#)
- [Patient Monitoring and Diagnostics](#)
- [Imaging](#)

## 3 Description

The TDES9640 is a V<sup>3</sup>Link Enhanced Vision deserializer that delivers robust ultra-high-speed 7.55 Gbps forward channel and 47.1875 Mbps bidirectional control channel for connecting up to 4 data sensors to the processing unit over a coaxial or STP cable. When paired with the TSER9615 or the TSER4905 serializers, the TDES9640 receives video data from image sensors or video sources supporting ultra-high resolutions or multiple sensors in various topologies.

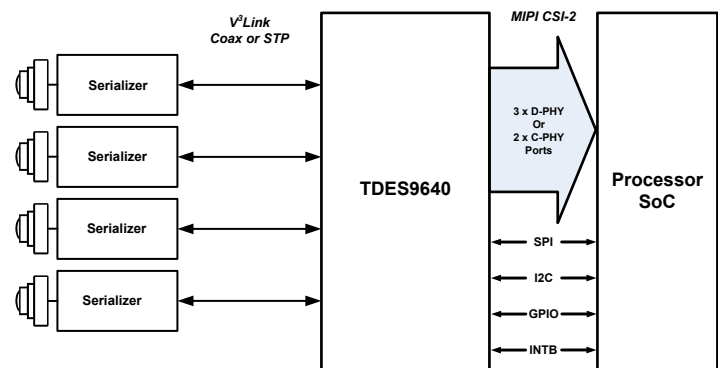
Data is received and aggregated into two MIPI CSI-2 D-PHY or C-PHY outputs for interfacing with a downstream processor. An additional CSI port is used for port replication in D-PHY mode only. The flexible MIPI CSI-2 outputs support multiple virtual channels interleaving per port to differentiate multiple sensors, exposures, and data types. This functionality features video aggregation and replication modes and supports input-to-output port as well as virtual channel (VC-ID) remapping.

The TDES9640 supports advanced data protection and diagnostic features, as well as multiple levels of data integrity checking and protection in conjunction with programmable health status interrupt, which helps achieve robust sensor module and link operation in the end application.

### Device Information

PART NUMBER	PACKAGE <sup>(1)</sup>	BODY SIZE (NOM)
TDES9640	VQFN (88)	12.00 mm × 12.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Typical Application Schematic

## 4 Device and Documentation Support

### 4.1 Documentation Support

#### 4.1.1 Related Documentation

For related documentation see the following:

- [I2C Communication Over FPD-Link III with Bidirectional Control Channel](#)
- [I2C Bus Pull-Up Resistor Calculation](#)

### 4.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 4.3 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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### 4.4 Trademarks

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### 4.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 4.6 Glossary

[TI Glossary](#)

This glossary lists and explains terms, acronyms, and definitions.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TDES9640RURR</a>	Active	Production	VQFNP (RUR)   88	2500   LARGE T&R	Yes	Call TI   Nipdauag	Level-3-260C-168 HR	-20 to 85	T9640
TDES9640RURR.A	Active	Production	VQFNP (RUR)   88	2500   LARGE T&R	Yes	Call TI	Level-3-260C-168 HR	-20 to 85	T9640
<a href="#">TDES9640RURT</a>	Active	Production	VQFNP (RUR)   88	250   SMALL T&R	Yes	Call TI   Nipdauag	Level-3-260C-168 HR	-20 to 85	T9640
TDES9640RURT.A	Active	Production	VQFNP (RUR)   88	250   SMALL T&R	Yes	Call TI	Level-3-260C-168 HR	-20 to 85	T9640

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

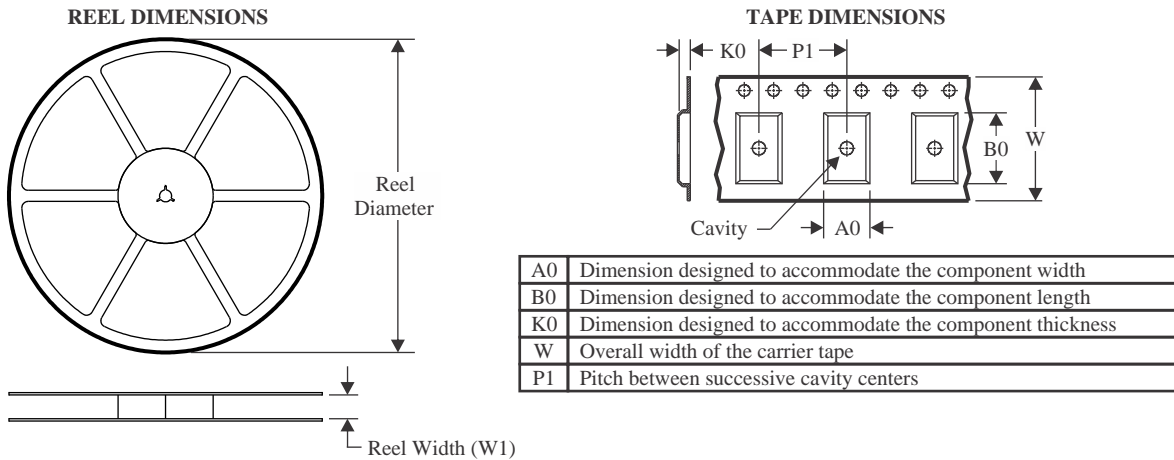
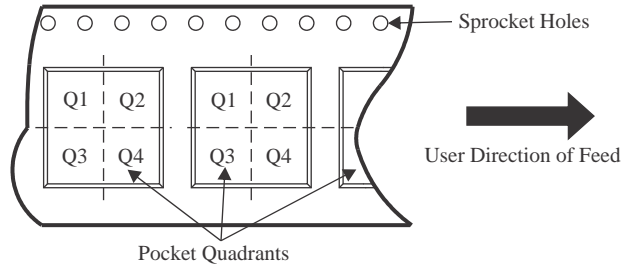
<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TDES9640RURR	VQFNP	RUR	88	2500	330.0	24.4	12.3	12.3	1.1	16.0	24.0	Q2

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TDES9640RURR	VQFNP	RUR	88	2500	367.0	367.0	45.0

## GENERIC PACKAGE VIEW

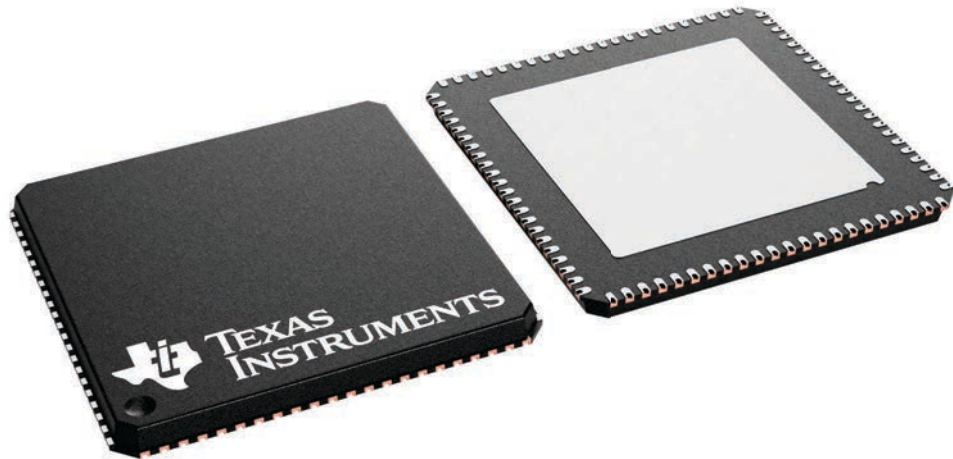
**RUR 88**

**VQFN - 0.9 mm max height**

12 x 12, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



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